

Heat conductive foam and gel foils

Gel thermal conducting foil

- highly heat-conductive silocon foil
- smooth, elastic and compressible
- equals uneven surfaces very well (Gap-Filler)



art. no.	material thickness [mm]	R _{th} [°C in ² /W]	UL 94
GEL 05	0.5 ±0.1	0.57	V-0
GEL 10	1.0 ±0.2	1.02	V-0
GEL 15	1.5 ±0.2	1.45	V-0
GEL 20	2.0 ±0.3	1.71	V-0
GEL 25	2.5 ±0.3	2.11	V-0
GEL 30	3.0 ±0.3	2.34	V-0
GEL 35	3.5 ±0.3	2.59	V-0
GEL 40	4.0 ±0.4	2.79	V-0
GEL 45	4.5 ±0.4	3.03	V-0
GEL 50	5.0 ±0.5	3.30	V-0
GEL G05	0.5 ±0.1	0.67	V-1
GEL G1	1.0 ±0.2	1.11	V-1
GEL G15	1.5 ±0.2	1.66	V-1
GEL G2	2.0 ±0.3	1.92	V-1
GEL G25	2.5 ±0.3	2.40	V-1
GEL G3	3.0 ±0.3	2.68	V-0
GEL G35	3.5 ±0.3	2.75	V-0
GEL G4	4.0 ±0.4	2.92	V-0
GEL G45	4.5 ±0.4	3.19	V-0
GEL G5	5.0 ±0.5	3.37	V-0

version:

art. no. **GEL ...** standard

art. no. **GEL G ...** GF reinforced, adherent layer on one side

delivery form:

plates, usable plain 300 X 200 mm, covered with protection film on booth sides, cuttings on customer's requirements

Technical data

	GEL	GEL G
thermal conductivity	1.5	1.5
volume resistance	> 1x10 ⁶ MΩ/m	> 1x10 ⁶ MΩ/m
hardness range	< 49 Shore 00	< 49 Shore 00
temperature range	-60 °C ... + 200 °C	-60 °C ... + 200 °C
extensibility	100 %	60 %
dielectric constant	5.8 [50 Hz] / 5.6 [1 KHz] / 5.5 [1 MHz]	5.8 [50 Hz] / 5.6 [1 KHz] / 5.5 [1 MHz]
breakdown voltage	14 kV/mm (AC)	8 kV/mm (AC)
tightness	2.6 g/cm ³	2.6 g/cm ³
dielectric loss factor	0.048 [50 Hz] / 0.015 [1 KHz] / 0.003 [1 MHz]	0.048 [50 Hz] / 0.015 [1 KHz] / 0.003 [1 MHz]

E 7

Thermal conductive glue
Thermal conductive paste
Thermal conduct. foil WLFT 404/405
SMD-heatsinks

→ E 15
 → E 13
 → E 5
 → B 38 – 40

Heatsinks for PGA
Profiles for PCB mounting
Mounting for TO 3 angle
Profiles for lock-in fixing spring

→ B 10 – 15
 → A 89 – 110
 → A 122
 → A 85 – 88